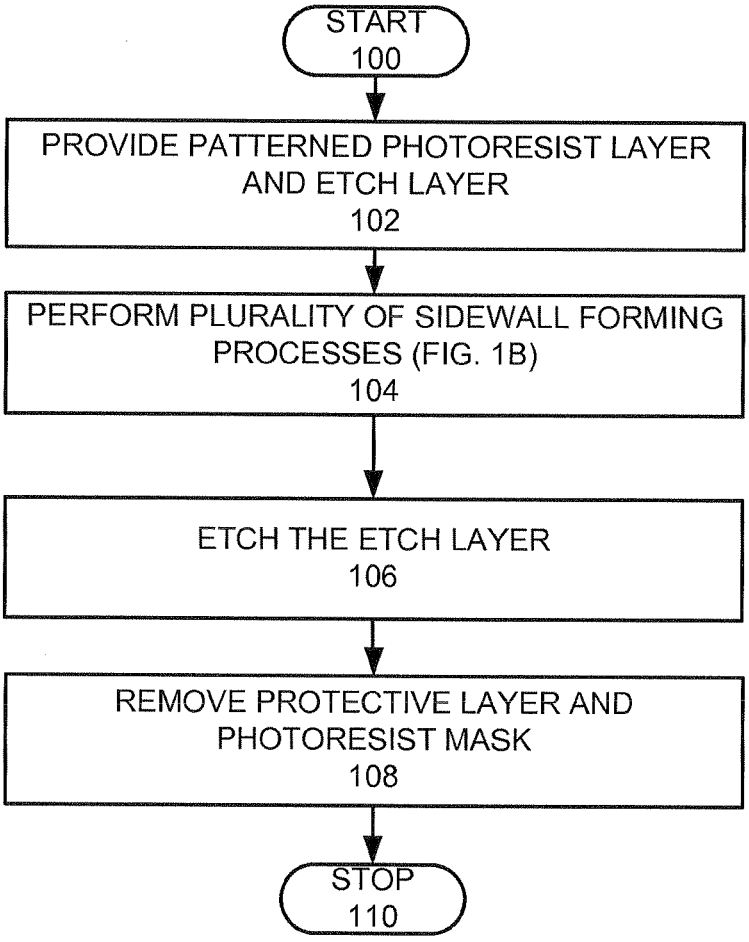

START
100
PROVIDE PATTERNED PHOTORESIST LAYER AND ETCH LAYER
102
PERFORM PLURALITY OF SIDEWALL FORMING PROCESSES (FIG. 1B)
104
ETCH THE ETCH LAYER
106
REMOVE PROTECTIVE LAYER AND PHOTORESIST MASK
108
STOP
110

FIG. 1A

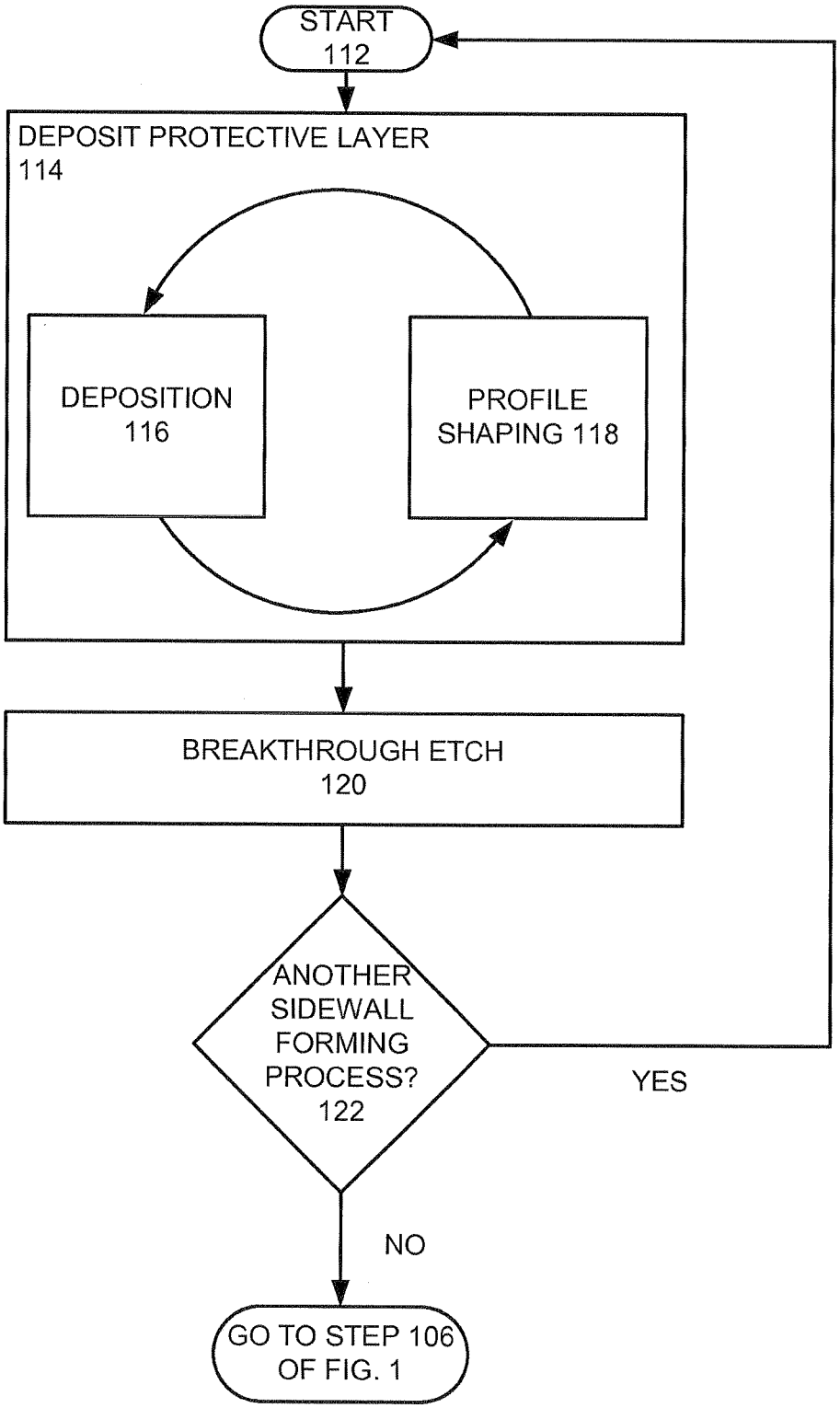

START
112
DEPOSIT PROTECTIVE LAYER
114
DEPOSITION
116
PROFILE
SHAPING 118
BREAKTHROUGH ETCH
120
ANOTHER
SIDEWALL
FORMING
PROCESS?
122
YES
NO
GO TO STEP 106
OF FIG. 1

FIG. 1B

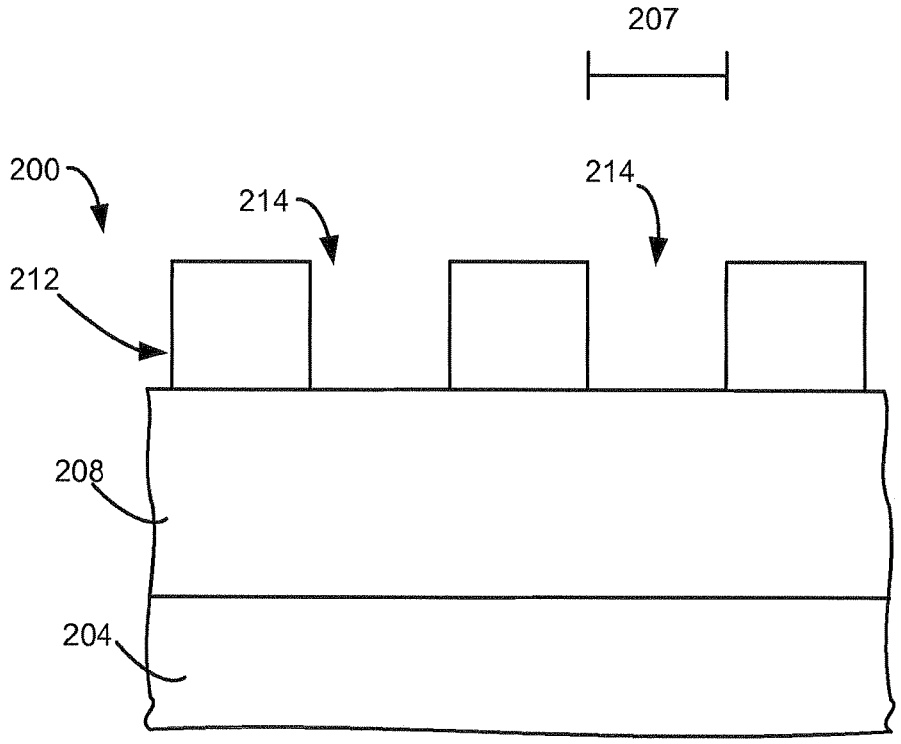

207
200
214
214
212
208
204

FIG. 2A

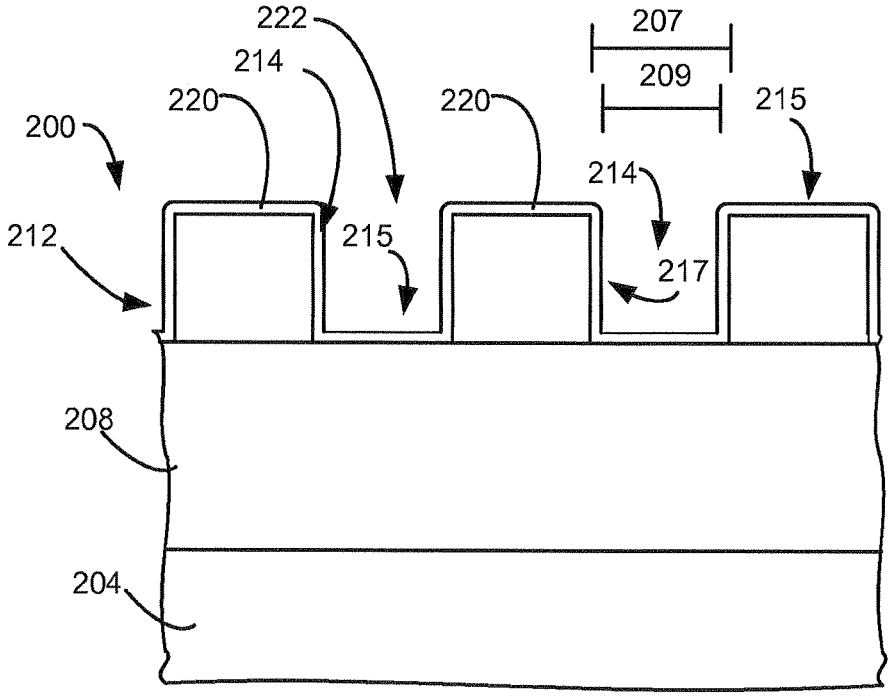

222
207
214
209
220
220
215
200
214
212
215
217
208
204

FIG. 2B

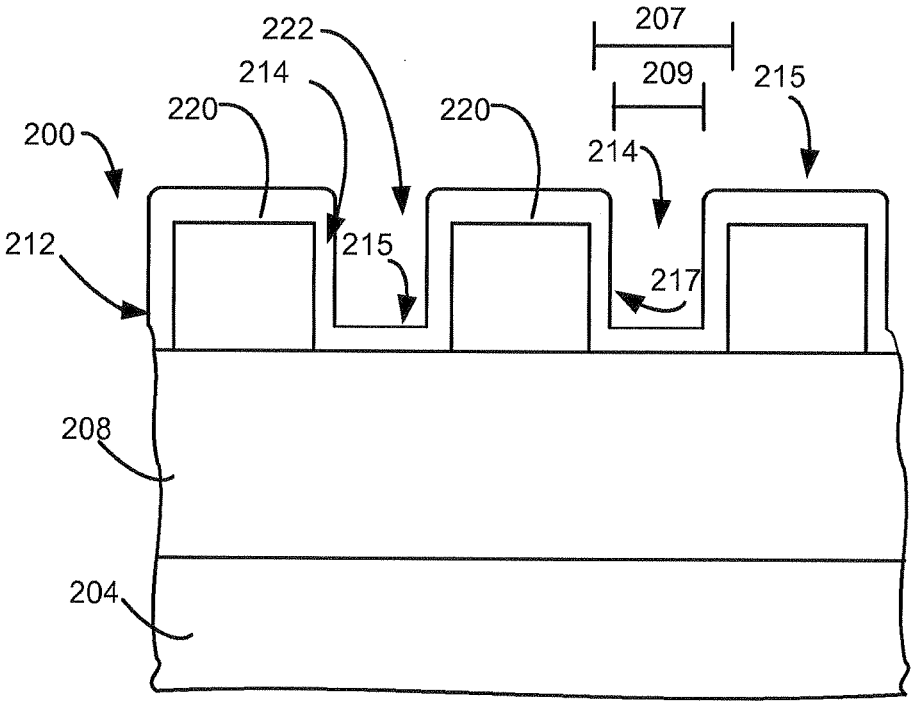

222
207
214
209
215
220
220
200
214
212
215
217
208
204

FIG. 2C

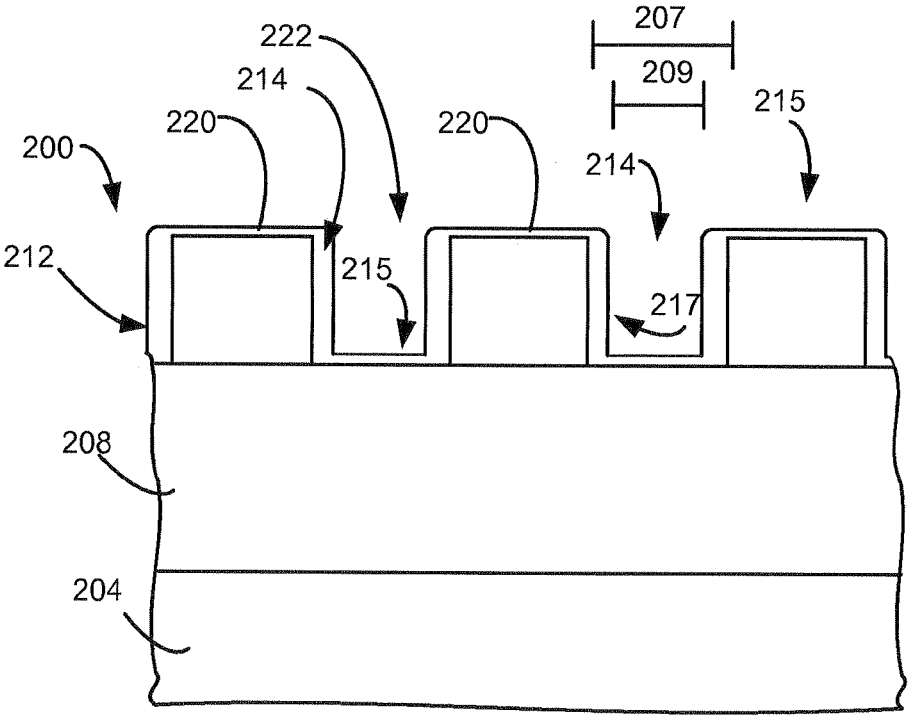

222
207
214
209
215
220
220
200
214
212
215
217
208
204

FIG. 2D

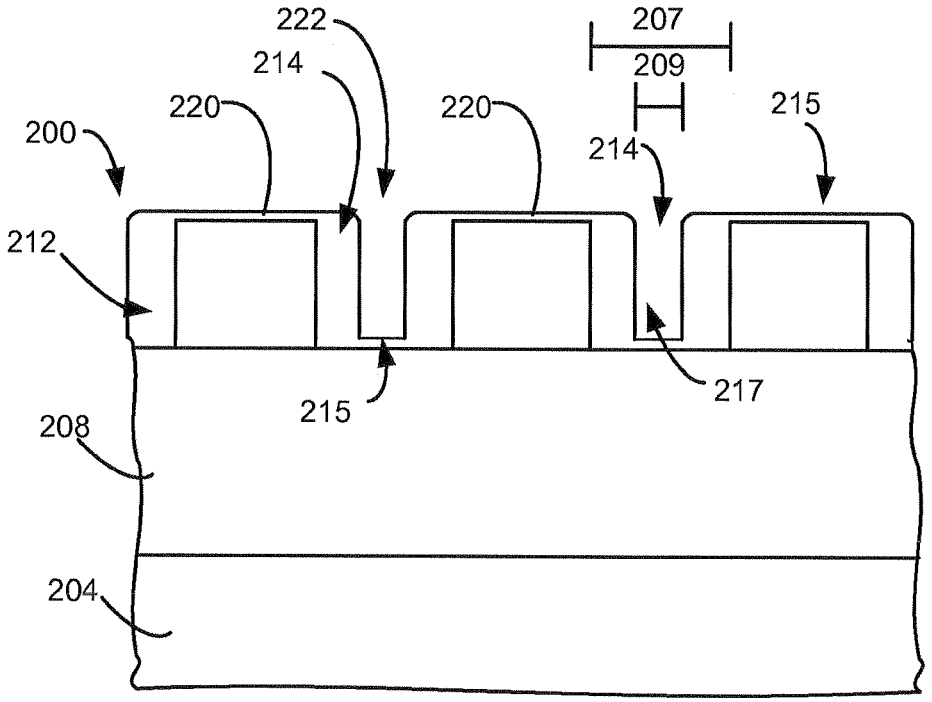

222
214
220
200
212
220
207
209
215
214
217
215
208
204

FIG. 2E

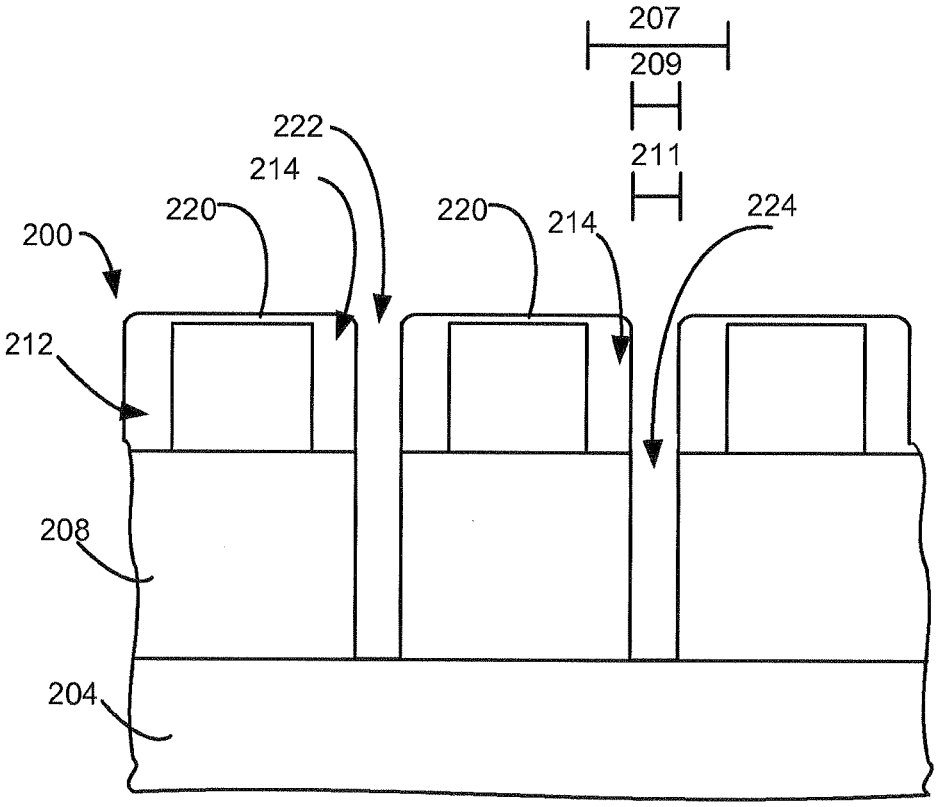

207
209
211
222
214
220
200
212
220
214
224
208
204

FIG. 2F

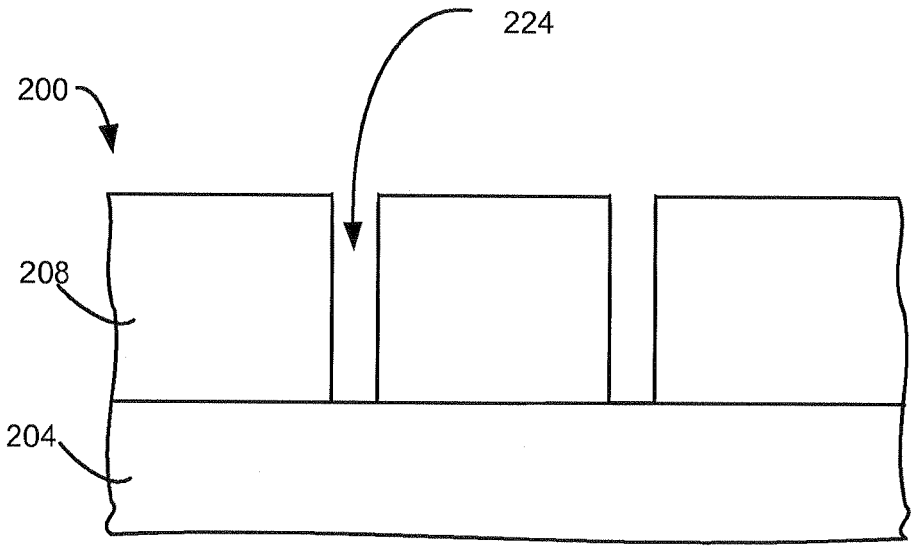


FIG. 2G

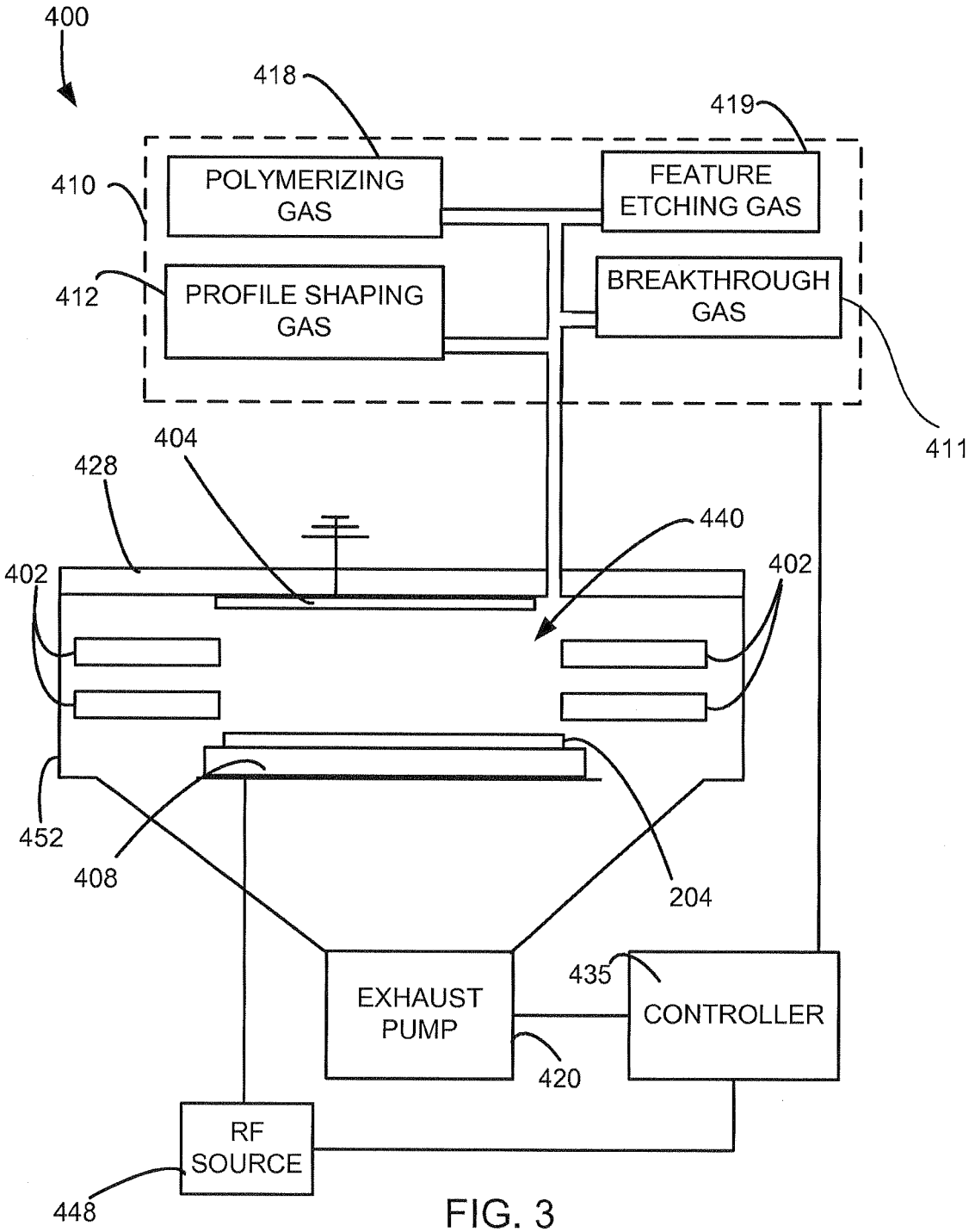

400
418
419
410
POLYMERIZING GAS
FEATURE ETCHING GAS
412
PROFILE SHAPING GAS
BREAKTHROUGH GAS
411
404
428
440
402
402
452
408
204
435
EXHAUST PUMP
CONTROLLER
420
RF SOURCE
448

FIG. 3

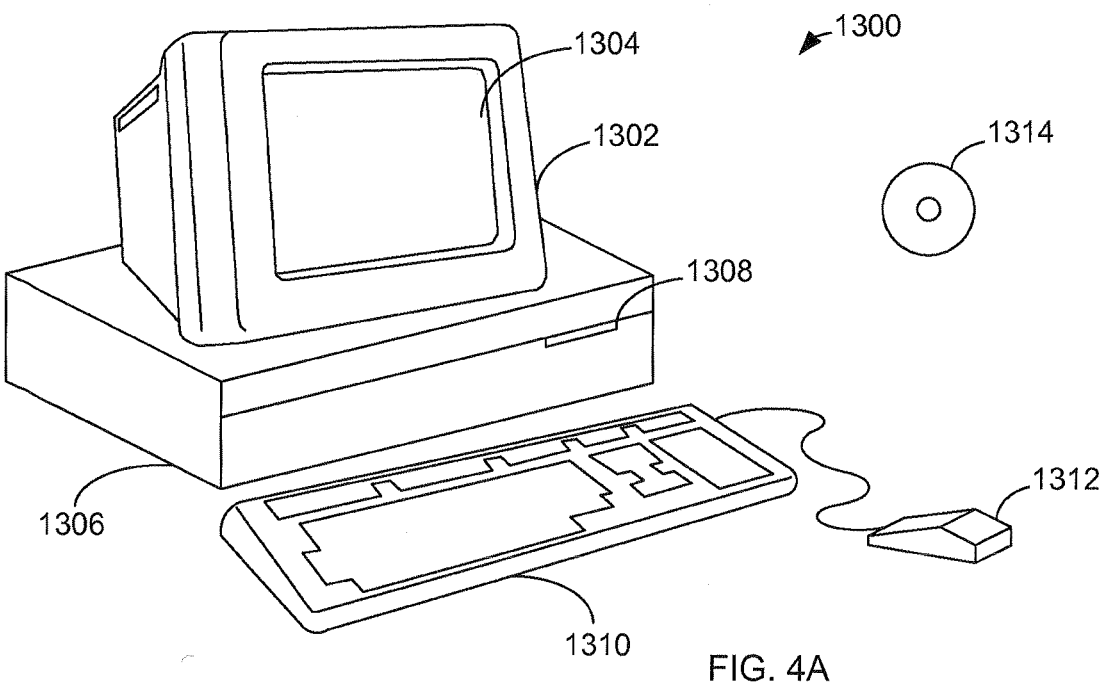

1300
1304
1302
1314
1308
1312
1306
1310

FIG. 4A

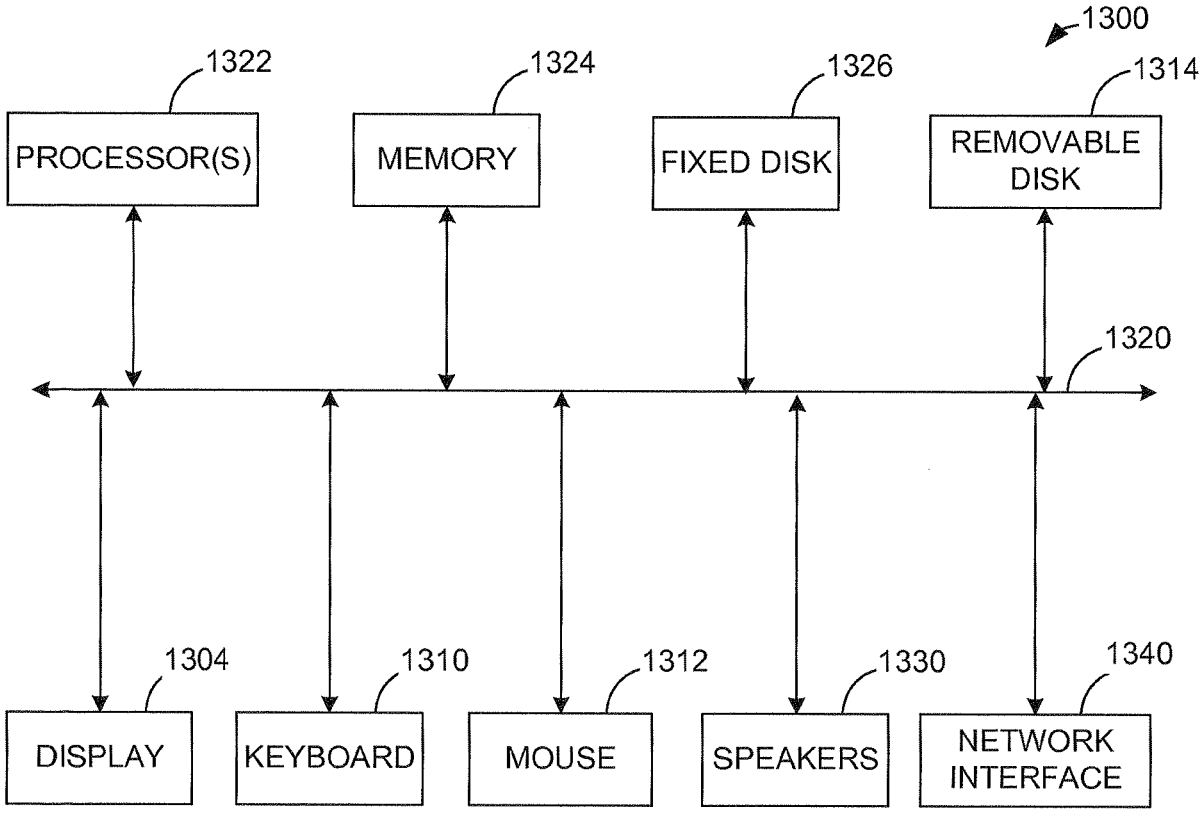

1300
1322
1324
1326
1314
PROCESSOR(S)
MEMORY
FIXED DISK
REMOVABLE DISK
1320
1304
1310
1312
1330
1340
DISPLAY
KEYBOARD
MOUSE
SPEAKERS
NETWORK INTERFACE

FIG. 4B